

● WLP-6-01 Power Dissipation

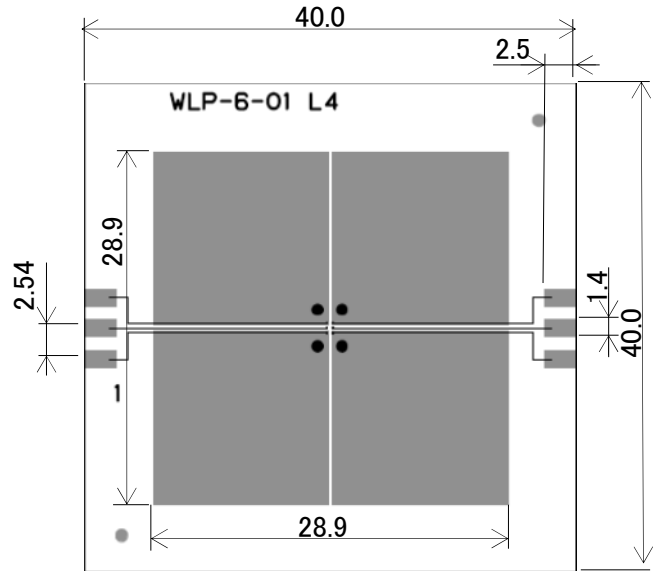
Power dissipation data for the WLP-6-01 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: 40mm×40mm (1600mm² in one side)
- Metal Area: 1st Metal Layer about 50%
2nd Inner Metal Layer about 50%
3rd Inner Metal Layer about 50%
4th Metal Layer about 50%
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6mm
- Through-hole: 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount ($T_j \text{ max}=125^\circ\text{C}$)

Ambient Temperature ($^\circ\text{C}$)	Power Dissipation P_d (mW)	Thermal Resistance ($^\circ\text{C}/\text{W}$)
25	700	142.86
85	280	

